

SO24



PACKAGE MATERIAL LIST

item #	material	thickness	thermal conductivity
leadframe	copper	0.25 mm	2.61 W/cm°C
die attach	epoxy glue (silver filler)	10-40 µm	0.01 W/cm°C
molding compound	epoxy resin	2.55 mm	0.0063W/cm°C

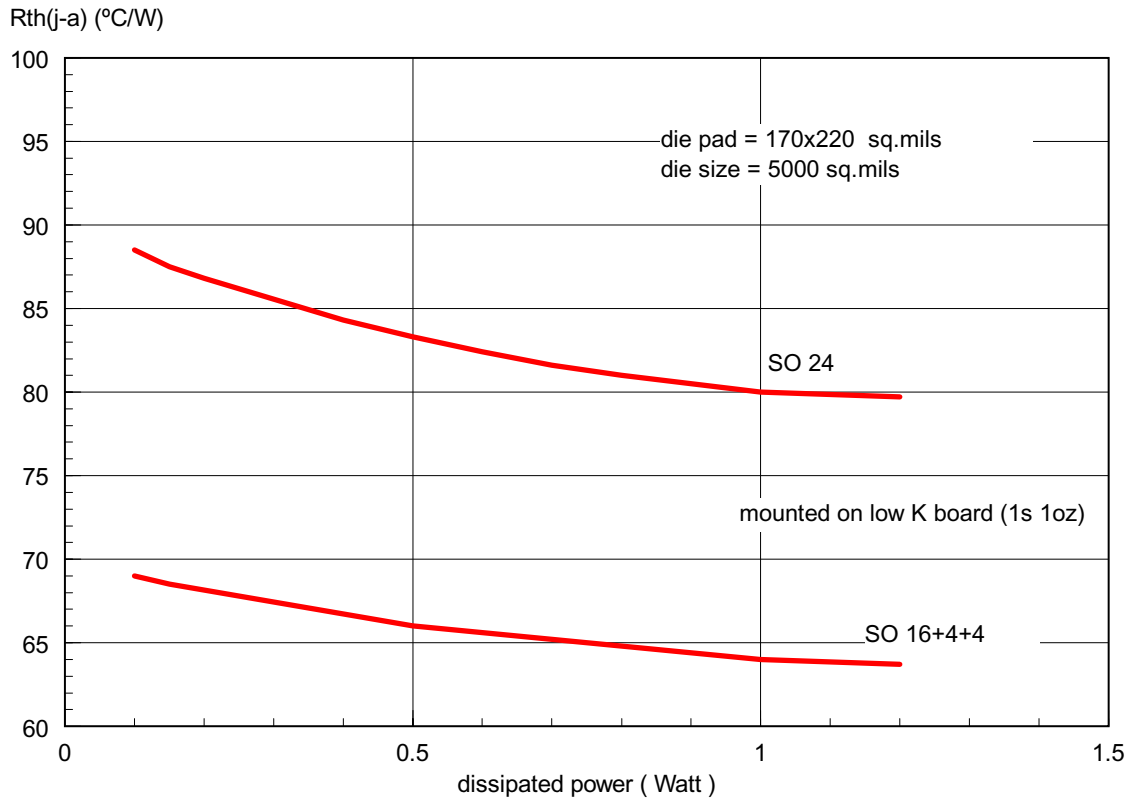
Leadframe options:

- i) 24 floating leads
- ii) 16+4+4 batwing
- iii) 18+3+3 batwing
- iv) 20+2+2 batwing

Charts enclosed :

- 1) $R_{th}(j-a)$ vs power dissipation
- 2) $Z_{th}(j-a)$ vs time

1)



2)

